IEEE WINTECHCON 2023

Thursday, September 21, 2023
The Leela Palace, Old Airport Road, Bengaluru

Technical Conference by Women in Engineering

CALL FOR PAPERS

Theme
Emerging Technologies from Silicon to Software for a Sustainable Future

Objective
Provide opportunities for women leaders in technology to present their work in emerging technical fields

Organized by: IEEE CAS Bangalore Chapter, IEEE Bangalore Section, WIE AG Bangalore Section

FOCUS AREA

The conference will focus on **architecture, algorithm, design, IP, verification, implementation, test, reliability and safety in software, hardware and systems** aspects of the following technology/product areas and their adjacencies. Papers, tutorials, and project demos are being sought in each of these areas.

- Artificial Intelligence/Machine Learning - Neural Networks, Deep Learning, Data Analytics, Big Data (Applications with model tuning, algorithms and optimization), AI-Enabled Systems, Accelerators (software/hardware)
- Compute at Scale - Hyperscale, Cloud, Cognitive, Mobile, Edge, Quantum, Virtualization, Service Mesh, Microservices, Heterogenous Architecture, Cloud Scale Workload Optimizations
- Communication - Wireless, Networking (WAN, LAN, Mobile, 5G, Wi-Fi 6E, MIMO, MM wave, Antenna, RF, photonics), Wired (Data centre) networking, trends in Ethernet, Switching, Sensor networking, Mobile devices, connectivity
- VLSI, IC Manufacturing and Fabrication
- Electronic Design Automation (compilers, modelling, tools)
- IoT - Industrial 4.0, Digital Healthcare, Wearables, Smart cities, Decentralized Security, Sensor design
- User Experience – Multimedia, Camera, Display, Video, Voice, Gaming and Music
- Automotive - Radar, ADAS, Safety, Battery Management, Electrification, Cabin Infotainment, Connectivity, Human Machine Interface, Vehicle to Everything, Vehicle Analytics
- Security and Privacy - Cyber Security, Cryptography, Hardware and Software Trusted Management
- Compute for Social Good - Sustainable/Green Compute, Net Zero
- Application, Architectural and Optimizing Inventions in Quantum Computing, Blockchain, Distributed Ledger
- Augmented Reality (AR) / Virtual Reality (VR) Technologies
- Advancement in Location/Navigation Product Based Technologies
- Consumer Electronics
- Robotics

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TECHNICAL PAPERS

Papers focusing on innovation, inventions, distinguished improvements in state-of-the-art, as well as aiming at cross pollination of practicing ideas, surveys, production strategies, flows, methodologies, process improvements and/or knowledge that are applied in product development in any of the aforementioned areas.

Format of Submission

▸ Primary author must be a FEMALE.
▸ Each paper must be in PDF within a limit of 6 A4 sheets in double column, including figures and tables in IEEE conference format.
  https://www.ieee.org/conferences/publishing/templates.html

TUTORIALS

▸ Tutorials focusing on current, relevant and practical hands-on topics in aforementioned areas that offer immediate value and learning for the attendees.
▸ Should include the title, abstract (300 words) and the biography of the presenters.
▸ Abstract should include topic relevance, high-level details on the tutorial structure and key take-away.
▸ It is expected that the authors are proficient in the subject and/or have several years of work experience in the domain.
▸ Tutorials may have no more than 2 presenters including one female presenter.

PROJECT DEMO

▸ Background and objective of the project, the problem description which the project attempts to solve, steps/details of methodology and format/results of the demonstration, audience takeaway should be covered.
▸ Presenters must bring the working model of the demo (software or hardware)
▸ Should include the title, abstract (300 words) and the biography of the presenters.
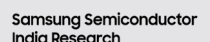▸ Demos may have no more than 2 presenters including one female presenter.

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POINTS TO REMEMBER

▸ The primary author/presenter of the paper must be a FEMALE. Co-authors/co-presenters can be a MALE or FEMALE.

▸ Professionals from the technology industry (semiconductor/hardware/software) and academic may submit.

▸ All the co-authors must be shown in the initial submission. No further authors can be added for selected papers. Maximum 6 members (including primary author, co-author) is permitted per submission.

▸ **Submission deadline (final) extended to May 15, 2023**, and all authors will be notified on the status of acceptance by July 28, 2023.

▸ Technical paper submissions can be accepted either for paper presentation or poster presentation, based on discretion of TPC. The final PPT should be formatted accordingly, based on acceptance notification.

▸ If a manuscript is accepted for paper presentation, the authors will be expected to also submit a final version of the manuscript that will be added to IEEE proceedings.

IMPORTANT DATES

▸ **Extended Deadline (final) for submission of Papers/Tutorials/Demos – May 15, 2023**
▸ Communication of acceptance to authors – July 28, 2023
▸ Conference – September 21, 2023

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https://cmt3.research.microsoft.com/IEEEWINTECHCON2023/Submission/Index

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